

# **SD1275**

# **RF & MICROWAVE TRANSISTORS** VHF MOBILE APPLICATIONS

■ 160 MHz ■ 13.6 VOLTS COMMON EMITTER ■ P<sub>OUT</sub> = 40 W MIN. WITH 9.0 dB GAIN .380 4L STUD (M135) epoxy sealed ORDER CODE BRANDING SD1275 SD1275 **PIN CONNECTION** 2 4 The SD1275 is a 13.6 V Class C epitaxial silicon 3 1. Collector 3. Emitter 2. Base 4. Base

#### DESCRIPTION

NPN planar transistor designed primarily for VHF communications. The SD1275 utilizes an emitter ballasted die geometry to withstand severe load mismatch conditions.

# **ABSOLUTE MAXIMUM RATINGS** ( $T_{case} = 25^{\circ}C$ )

Symbol	Parameter	Value	Unit
Vсво	Collector-Base Voltage	36	V
V <sub>CEO</sub>	Collector-Emitter Voltage	16	V
V <sub>CES</sub>	Collector-Emitter Voltage	36	V
Vebo	Emitter-Base Voltage	4.0	V
lc	Device Current	8.0	А
P <sub>DISS</sub>	Power Dissipation	70	W
TJ	Junction Temperature	+200	°C
T <sub>STG</sub>	Storage Temperature	– 65 to +150	°C

## THERMAL DATA

R <sub>TH(j-c)</sub> Juncti	on-Case Thermal Resistance	1.2	°C/W
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# SD1275

# **ELECTRICAL SPECIFICATIONS** ( $T_{case} = 25^{\circ}C$ )

#### STATIC

Symbol	Test Conditions		Value			Unit	
			Min.	Тур.	Max.	Unit	
BVCES	I <sub>C</sub> = 15mA	$V_{BE} = 0mA$		36	_		V
BVCEO	Ic = 50mA	$I_B = 0mA$		16			V
$BV_{EBO}$	$I_E = 5mA$	$I_C = 0mA$		4.0			V
I <sub>CBO</sub>	$V_{CB} = 15V$	$I_E = 0mA$			—	5	mA
hFE	$V_{CE} = 5V$	$I_C = 250 \text{mA}$		20	—		

#### DYNAMIC

Symbol	Tost Conditions		Value			Unit	
Symbol	Test conditions			Min.	Тур.	Max.	omit
Роит	f = 160 MHz	$P_{IN} = 5.0 \text{ W}$	$V_{CE} = 13.6$ V	40	_		W
GP	f = 160 MHz	$P_{IN} = 5.0 \text{ W}$	Vce = 13.6 V	9	_	—	dB
Сов	f = 1 MHz	V <sub>CB</sub> = 15 V	Car Oliv	—	95	—	pF
TYPICAL PERFORMANCE							

#### TYPICAL PERFORMANCE

# POWER GAIN vs FREQUENCY



# POWER OUTPUT vs POWER INPUT





# **TYPICAL PERFORMANCE (cont'd)**



#### **IMPEDANCE DATA**

FREQ.	Ζιν (Ω)	Zcl (Ω)
160 MHz	1.0 + j 0.4	2.3 + j 0.1
$P_{IN} = 3.0 \text{ W}$		
V <sub>CE</sub> = 12.5 V		



#### SD1275

#### PACKAGE MECHANICAL DATA



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